

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC030N03MS G	**Issued**	31. January 2019
MA#	MA004818982		
Package	PG-TDSON-8-39	**Weight***	112.59 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.840	1.63	1.63	16344	16344
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.048	0.04		430	
	non noble metal	copper	7440-50-8	48.352	42.97	43.02	429461	430020
wire	non noble metal	copper	7440-50-8	0.045	0.04	0.04	396	396
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		734	
	plastics	epoxy resin	-	6.531	5.80		58004	
	inorganic material	silicondioxide	60676-86-0	34.719	30.84	36.71	308373	367111
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13501	13501
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1407	1407
solder	non noble metal	tin	7440-31-5	0.038	0.03		337	
	noble metal	silver	7440-22-4	0.047	0.04		421	
	non noble metal	lead	7439-92-1	1.813	1.61	1.68	16099	16857
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2639	2643
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1332	
	non noble metal	copper	7440-50-8	16.910	15.02	15.17	150194	151721
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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